

Appl. No. 10/755,042  
Amdt. dated March 23, 2007  
Reply to Office action of January 04, 2007

### REMARKS/ARGUMENTS

The Examiner is thanked for the thorough examination and for finding previously-presented Claims 179-208 allowable

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Claims 163-208 are pending; Claims 1-162 are canceled.

#### Response to Claim Rejections under 35 U.S.C. 102 and 103

10 Applicants respectfully traverse the rejections for at least the reasons set forth below.

#### **Response to Claims 163-178**

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As previously presented, independent claim 163 is recited below:

163. A chip package comprising:

a substrate comprising silicon;

a die joined with said substrate; and

20 a metallization structure over said die, wherein said metallization structure comprises an electroplated metal.

25 *Reconsideration of Claim 163-178 rejected under 35 U.S.C. 102(e) as being anticipated by Eichelberger et al. (US 6,396,148) is requested based on the following remarks.*

Appl. No. 10/755,042  
Amdt. dated March 23, 2007  
Reply to Office action of January 04, 2007

Applicants respectfully assert that the chip package claimed in claim 163 patentably distinguishes over the citation by Eichelberger et al. (US 6,396,148).

5 Eichelberger et al. teach a chip package comprising a substrate 101, a die 102 joined with said substrate 101, and a metallization structure 108 over said die 102. ~ See FIG 1 and col. 4, lines 9-22 ~

However, Eichelberger et al. fail to teach, hint or suggest that said metallization structure 108 may comprise an electroplated metal.

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The Examiner considers that "electroless metal and electroplated metal are synonymous". ~ See the first paragraph, on page 6, in the last Office Action mailed Jan. 4, 2007 ~

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Applicants respectfully traverse the Examiner's opinion. "Electroless" means "being or involving deposition of metal by chemical means instead of by electrodeposition". "Electroplate" means "to plate with an adherent continuous coating by electrodeposition". The meanings of "electroless" and "electroplate" are significantly different from each other. It is believed that "electroless metal" is non-analogous to "electroplated metal".

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Withdrawal of the rejection under 35 U.S.C. 103(e) to Claim 163 is respectfully requested.

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For at least the foregoing reasons, applicants respectfully submit independent claim 163 patently distinguishes over the prior art references, and should be allowed. For at least the same reasons, dependent claims 164-178 patently define over the prior art as well.

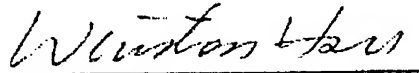
Appl. No. 10/755,042  
Amdt. dated March 23, 2007  
Reply to Office action of January 04, 2007

CONCLUSION

Some or all of the pending claims are believed to be in condition for allowance.  
Accordingly, allowance of the claims and the application as a whole are respectfully  
requested.

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Sincerely yours,



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15 Note: Please leave a message in my voice mail if you need to talk to me. (The time in D.C.  
is 12 hours behind the Taiwan time, i.e. 9 AM in D.C. = 9 PM in Taiwan.)